

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT4595489

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
MINGZHU WANG	08/24/2017
BOJIE ZHAO	08/23/2017
ZHENYU CHEN	08/23/2017
TAKEHIKO TANAKA	08/24/2017
NAN GUO	08/24/2017
ZHEN HUANG	08/24/2017
DUANLIANG CHENG	08/24/2017
LIANG DING	08/23/2017
FEIFAN CHEN	08/23/2017
HENG JIANG	08/25/2017
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	NINGBO SUNNY OPOTECH CO., LTD.
<b>Street Address:</b>	66-68, SHUNYU ROAD, YUYAO CITY,
<b>City:</b>	NINGBO, ZHEJIANG
<b>State/Country:</b>	CHINA
<b>Postal Code:</b>	315400
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	15460216
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(626)571-9813
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	626-571-9812
<b>Email:</b>	RAYMONDC@DAVIDANDRAYMOND.COM
<b>Correspondent Name:</b>	DAVID AND RAYMOND PATENT FIRM
<b>Address Line 1:</b>	108 N. YNEZ AVE., SUITE 128
<b>Address Line 4:</b>	MONTEREY PARK, CALIFORNIA 91754
<b>ATTORNEY DOCKET NUMBER:</b>	USCP10130C/NB2926-SYO

<b>NAME OF SUBMITTER:</b>	MICHAEL LEE
<b>SIGNATURE:</b>	/Michael Lee/
<b>DATE SIGNED:</b>	09/14/2017
<b>Total Attachments: 10</b> source=USCP10130assignment#page1.tif source=USCP10130assignment#page2.tif source=USCP10130assignment#page3.tif source=USCP10130assignment#page4.tif source=USCP10130assignment#page5.tif source=USCP10130assignment#page6.tif source=USCP10130assignment#page7.tif source=USCP10130assignment#page8.tif source=USCP10130assignment#page9.tif source=USCP10130assignment#page10.tif	

## ASSIGNMENT

WHEREAS, I (we), Mingzhu Wang  
whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented a  
certain new and useful improvements in  
Array Imaging Module and Molded Photosensitive Assembly, Circuit Board Assembly and Manufacturing  
Methods Thereof for Electronic Device  
(hereinafter referred to as the INVENTION) for which an application for United States Letters Patent was

executed on even data herewith

executed on:

filed on: 03/15/2017

Serial No.: 15/460,216

WHEREAS, Ningbo Sunny Opotech Co.,Ltd.  
whose post office address is 66-68 Shunyu Road, Yuyao City, Ningbo, Zhejiang Province, China 315400  
hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the  
same in the United States;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby  
acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the  
entire right, title, and interest in and to said INVENTION and application throughout the United States of  
America, including any and all Letters Patent granted on any division, continuation, continuation-in-part  
and reissue of said application.

ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in  
connection with the filing, prosecution and maintenance of said application or any other patent  
application(s) in the United States for said INVENTION, including additional documents that may be  
required to affirm the rights of ASSIGNEE in and to said INVENTION, all without further consideration.  
ASSIGNOR also agrees, without further consideration and at ASSIGNEE'S expense, to identify and  
communicate to ASSIGNEE at ASSIGNEE'S request documents and information concerning the INVENTION  
that are within ASSIGNOR'S possession or control, and to provide further assurances and testimony on  
behalf of ASSIGNEE that lawfully may be required of ASSIGNOR in respect of the prosecution, maintenance  
and defense of any patent application or patent encompassed within the terms of this instrument.  
ASSIGNOR'S obligations under this instrument shall extend to ASSIGNOR'S heirs, executors, administrators  
and other legal representatives.

ALSO, ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to  
issue any and all Letters Patent referred to above to ASSIGNEE, as the ASSIGNEE of the entire right, title  
and interest in and to the same, for ASSIGNEE'S sole use and behoof; and for the use and behoof of  
ASSIGNEE'S legal representatives and successors, to the full end of the term for which such Letters Patent  
may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment  
and sale not been made.

ASSIGNOR authorizes Raymond Y. Chan to insert or complete any information in this document  
needed to effect its recordal in the U.S. Patent and Trademark Office.

ASSIGNOR NAME: Mingzhu Wang  
ADDRESS: 66-68 Shunyu Road, Yuyao City, Ningbo, Zhejiang Province, China 315400

SIGNATURE

*Mingzhu Wang*

DATE

2017. 8. 24.

## ASSIGNMENT

WHEREAS, I (we), Bojie Zhao  
whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented a  
certain new and useful improvements in  
Array Imaging Module and Its Molded Photosensitive Assembly, Circuit Board Assembly, and  
Manufacturing Methods Thereof for Electronic Device  
(hereinafter referred to as the INVENTION) for which an application for United States Letters Patent was

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ASSIGNOR NAME: Bojie Zhao

ADDRESS: 66-68 Shunyu Road, Yuyao City, Ningbo, Zhejiang Province, China 315400

SIGNATURE

Bojie Zhao

DATE

2017. 8. 23

**ASSIGNMENT**

WHEREAS, I (we), Zhenyu Chen  
whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented a  
certain new and useful improvements in  
Array Imaging Module and Molded Photosensitive Assembly, Circuit Board Assembly and Manufacturing  
Methods Thereof for Electronic Device  
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- filed on: 03/15/2017

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and sale not been made.

ASSIGNOR authorizes Raymond Y. Chan to insert or complete any information in this document  
needed to effect its recordal in the U.S. Patent and Trademark Office.

ASSIGNOR NAME: Zhenyu Chen  
ADDRESS: 66-68 Shunyu Road, Yuyao City, Ningbo, Zhejiang Province, China 315400

Zhenyu Chen  
SIGNATURE

2017.08.23  
DATE

**ASSIGNMENT**

WHEREAS, I (we), Takehiko Tanaka  
whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented a  
certain new and useful improvements in  
Array Imaging Module and Molded Photosensitive Assembly, Circuit Board Assembly and Manufacturing  
Methods Thereof for Electronic Device  
(hereinafter referred to as the INVENTION) for which an application for United States Letters Patent was

executed on even data herewith

executed on:

filed on: 03/15/2017

Serial No.: 15/460,216

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whose post office address is 66-68 Shunyu Road, Yuyao City, Ningbo, Zhejiang Province, China 315400  
hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the  
same in the United States;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby  
acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the  
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and sale not been made.

ASSIGNOR authorizes Raymond Y. Chan to insert or complete any information in this document  
needed to effect its recordal in the U.S. Patent and Trademark Office.

ASSIGNOR NAME: Takehiko Tanaka  
ADDRESS: 66-68 Shunyu Road, Yuyao City, Ningbo, Zhejiang Province, China 315400

Takehiko Tanaka  
SIGNATURE

2017.8.24  
DATE

**ASSIGNMENT**

WHEREAS, I (we), Nan Guo  
whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented a certain new and useful improvements in  
Array Imaging Module and Molded Photosensitive Assembly, Circuit Board Assembly and Manufacturing Methods Thereof for Electronic Device  
(hereinafter referred to as the INVENTION) for which an application for United States Letters Patent was

executed on even data herewith  
 executed on:  
 filed on: 03/15/2017                      Serial No.: 15/460,216

WHEREAS, Ningbo Sunny Opotech Co.,Ltd.  
whose post office address is 66-68 Shunyu Road, Yuyao City, Ningbo, Zhejiang Province, China 315400  
hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the United States;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said INVENTION and application throughout the United States of America, including any and all Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application.

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ASSIGNOR authorizes Raymond Y. Chan to insert or complete any information in this document needed to effect its recordal in the U.S. Patent and Trademark Office.

ASSIGNOR NAME: Nan Guo  
ADDRESS: 66-68 Shunyu Road, Yuyao City, Ningbo, Zhejiang Province, China 315400

Nan Guo  
SIGNATURE

2017. 8. 20  
DATE

**ASSIGNMENT**

WHEREAS, I (we), Zhen Huang  
whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented a  
certain new and useful improvements in  
Array Imaging Module and Molded Photosensitive Assembly, Circuit Board Assembly and Manufacturing  
Methods Thereof for Electronic Device  
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WHEREAS, Ningbo Sunny Opotech Co.,Ltd.  
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NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby  
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and interest in and to the same, for ASSIGNEE'S sole use and behoof; and for the use and behoof of  
ASSIGNEE'S legal representatives and successors, to the full end of the term for which such Letters Patent  
may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment  
and sale not been made.

ASSIGNOR authorizes Raymond Y. Chan to insert or complete any information in this document  
needed to effect its recordal in the U.S. Patent and Trademark Office.

ASSIGNOR NAME: Zhen Huang  
ADDRESS: 66-68 Shunyu Road, Yuyao City, Ningbo, Zhejiang Province, China 315400

SIGNATURE

*Zhen Huang*

DATE

*2017/8/24*



**ASSIGNMENT**

WHEREAS, I (we), Duanliang Cheng whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented a certain new and useful improvements in Array Imaging Module and Its Molded Photosensitive Assembly, Circuit Board Assembly, and Manufacturing Methods Thereof for Electronic Device (hereinafter referred to as the INVENTION) for which an application for United States Letters Patent was

executed on even data herewith

executed on:

filed on: 03/15/2017

Serial No.: 15/460,216

WHEREAS, Ningbo Sunny Opotech Co.,Ltd. whose post office address is 66-68 Shunyu Road, Yuyao City, Ningbo, Zhejiang Province, China 315400 hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the United States;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said INVENTION and application throughout the United States of America, including any and all Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application.

ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in connection with the filing, prosecution and maintenance of said application or any other patent application(s) in the United States for said INVENTION, including additional documents that may be required to affirm the rights of ASSIGNEE in and to said INVENTION, all without further consideration. ASSIGNOR also agrees, without further consideration and at ASSIGNEE'S expense, to identify and communicate to ASSIGNEE at ASSIGNEE'S request documents and information concerning the INVENTION that are within ASSIGNOR'S possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may be required of ASSIGNOR in respect of the prosecution, maintenance and defense of any patent application or patent encompassed within the terms of this instrument. ASSIGNOR'S obligations under this instrument shall extend to ASSIGNOR'S heirs, executors, administrators and other legal representatives.

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ASSIGNOR authorizes Raymond Y. Chan to insert or complete any information in this document needed to effect its recordal in the U.S. Patent and Trademark Office.

ASSIGNOR NAME: Duanliang Cheng  
ADDRESS: 66-68 Shunyu Road, Yuyao City, Ningbo, Zhejiang Province, China 315400

SIGNATURE

*Duanliang Cheng*

DATE

*2017. 8. 28*

**ASSIGNMENT**

WHEREAS, I (we), Liang Ding  
whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented a certain new and useful improvements in  
Array Imaging Module and Molded Photosensitive Assembly, Circuit Board Assembly and Manufacturing Methods Thereof for Electronic Device  
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ASSIGNOR NAME: Liang Ding  
ADDRESS: 66-68 Shunyu Road, Yuyao City, Ningbo, Zhejiang Province, China 315400

SIGNATURE

DATE

**ASSIGNMENT**

WHEREAS, I (we), Feifan Chen  
whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented a certain new and useful improvements in  
Array Imaging Module and Its Molded Photosensitive Assembly, Circuit Board Assembly, and Manufacturing Methods Thereof for Electronic Device  
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ASSIGNOR NAME: Feifan Chen  
ADDRESS: 66-68 Shunyu Road, Yuyao City, Ningbo, Zhejiang Province, China 315400

SIGNATURE

Feifan chen

DATE

2017.8.23

## ASSIGNMENT

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acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the  
entire right, title, and interest in and to said INVENTION and application throughout the United States of  
America, including any and all Letters Patent granted on any division, continuation, continuation-in-part and  
reissue of said application.

ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in  
connection with the filing, prosecution and maintenance of said application or any other patent application(s)  
in the United States for said INVENTION, including additional documents that may be required to affirm the  
rights of ASSIGNEE in and to said INVENTION, all without further consideration. ASSIGNOR also agrees,  
without further consideration and at ASSIGNEE'S expense, to identify and communicate to ASSIGNEE at  
ASSIGNEE'S request documents and information concerning the INVENTION that are within ASSIGNOR'S  
possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully  
may be required of ASSIGNOR in respect of the prosecution, maintenance and defense of any patent  
application or patent encompassed within the terms of this instrument. ASSIGNOR'S obligations under this  
instrument shall extend to ASSIGNOR'S heirs, executors, administrators and other legal representatives.

ALSO, ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to  
issue any and all Letters Patent referred to above to ASSIGNEE, as the ASSIGNEE of the entire right, title  
and interest in and to the same, for ASSIGNEE'S sole use and behoof, and for the use and behoof of  
ASSIGNEE'S legal representatives and successors, to the full end of the term for which such Letters Patent  
may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment  
and sale not been made.

ASSIGNOR authorizes Raymond Y. Chan to insert or complete any information in this document  
needed to effect its recordal in the U.S. Patent and Trademark Office.

ASSIGNOR NAME: Heng Jiang  
ADDRESS: 66-68 Shunyu Road, Yuyao City, Ningbo, Zhejiang Province, China 315400

Heng Jiang  
SIGNATURE

2017. 8. 25  
DATE